

推奨基板取付け寸法
 PC 基板厚: 1.6 ± 0.1
 (非累積公差)
 (コネクタ搭載面)

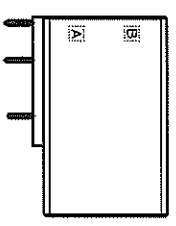
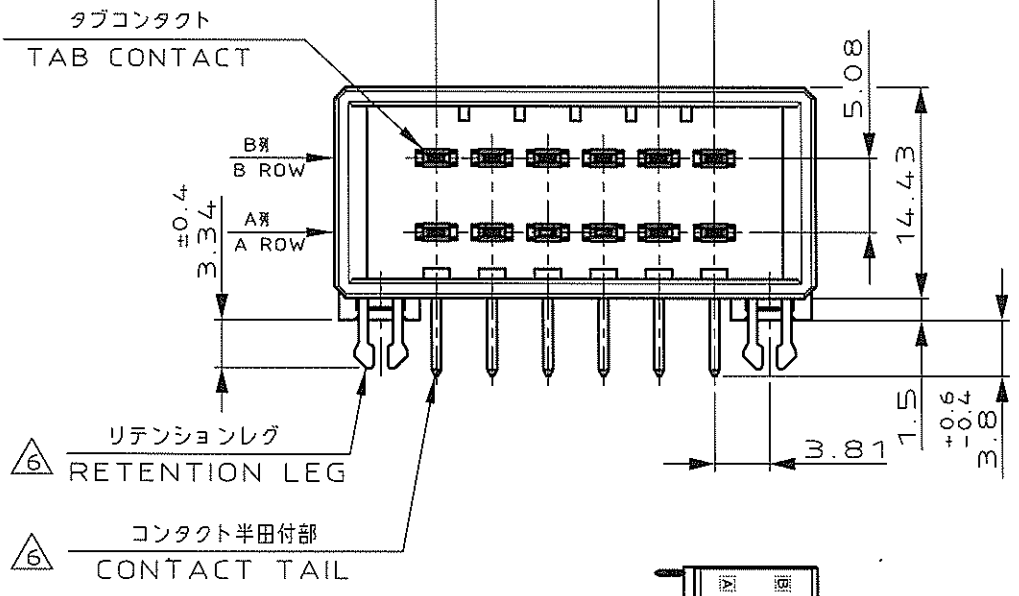
RECOMEND PC BOARD HOLE PATTERN
 PC BOARD THICKNESS: 1.6 ± 0.1
 (NOT ACCUMULATE TOLERANCE)
 (CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER
 CONTACT: COPPER ALLOY
 RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
 コネクタ: 銅合金
 リテンションレグ: 銅合金
- めっき: コネクタ: 全面Ni下地
 接触部: 0.38 μm MIN金めっき
- めっき: コネクタ: 全面Ni下地
 接触部: 0.76 μm MIN金めっき
- めっき: コネクタ: 全面Ni下地
 接触部: 2.0 μm MINスズめっき
- めっき: リテンションレグとコネクタ半田付部
 : ニッケル下地の上に半田めっき
- めっき: リテンションレグとコネクタ半田付部
 : ニッケル下地の上にスズめっき



VIEW A
 (SCALE: 1:1)

△6	△4	178306-5
△6	△3	178306-3
△6	△2	178306-2
(FINISH)		製品番号 (PART NO.)

B1	REVISED ECR-07-013273	TS	DM	11 JUN '95
B	REVISED (FJDO-0039-03)	TS	S.M	6/2 '03
A	REVISED (FJDO-0114-03)	TS	SM	25 APR '03
O	RELEASED FJ00-2528-95	NM	Y.I	6/30 '95
LTR	REVISION RECORD	DR	CHK	DATE

WIRE RANGE		INSULATION DIA		NAME	
mm(AWG) -		mmφ		12 POS DOUBLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC 3100	
MATERIAL SEE NOTE 注記参照		FINISH SEE NOTE 注記参照		一般公差 (GENERAL TOLERANCE)	
DR. 23 JUN 95 N. Matsubara		DE. 23 JUN 95 N. Matsubara		10% ±0.3 10% ±0.4 30% ±0.45 角 度 : ±3'	
CHK. 30 JUN 95 Y. ISHIKAWA		APP. 3 JUL 95 S. MANABE		SCALE 2-1	

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SIZE	LOC	NUMBER	C-178306		
A3	J		REV.	B1	SHEET 1 OF 1

NUMBER 178306
 METRIC
 3rd ANGLE PROJECTION
 PROJ NO. 395-612
 DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT
 PRINT DIST
 AMP-J
 REV. 10/83